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출판사 소개 및 수록내용

❑ 출판사 소개

기계공학 관련 한 American Society of Mechanical Engineers(ASME)는 Technical , educational and research issue를 추구하는 세계적인 Engineering Society 입니다.

❑ 수록내용

- 주제분야 : 기계공학
- 제공연도 : 1980 ~ 현재
- 제공종수 : 25종 + AMR Journal

ASME Webpage : http://www.asmedl.org/

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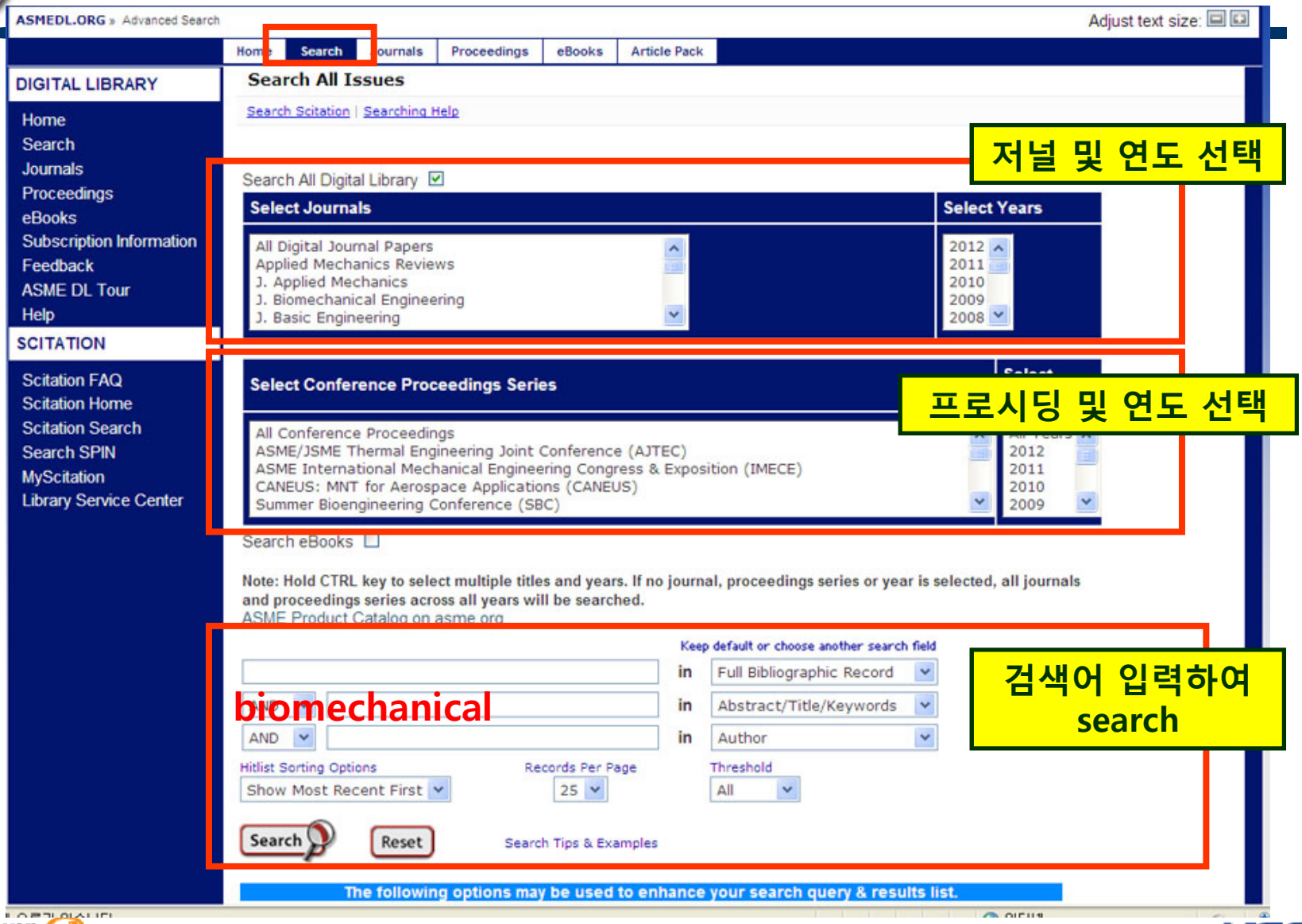
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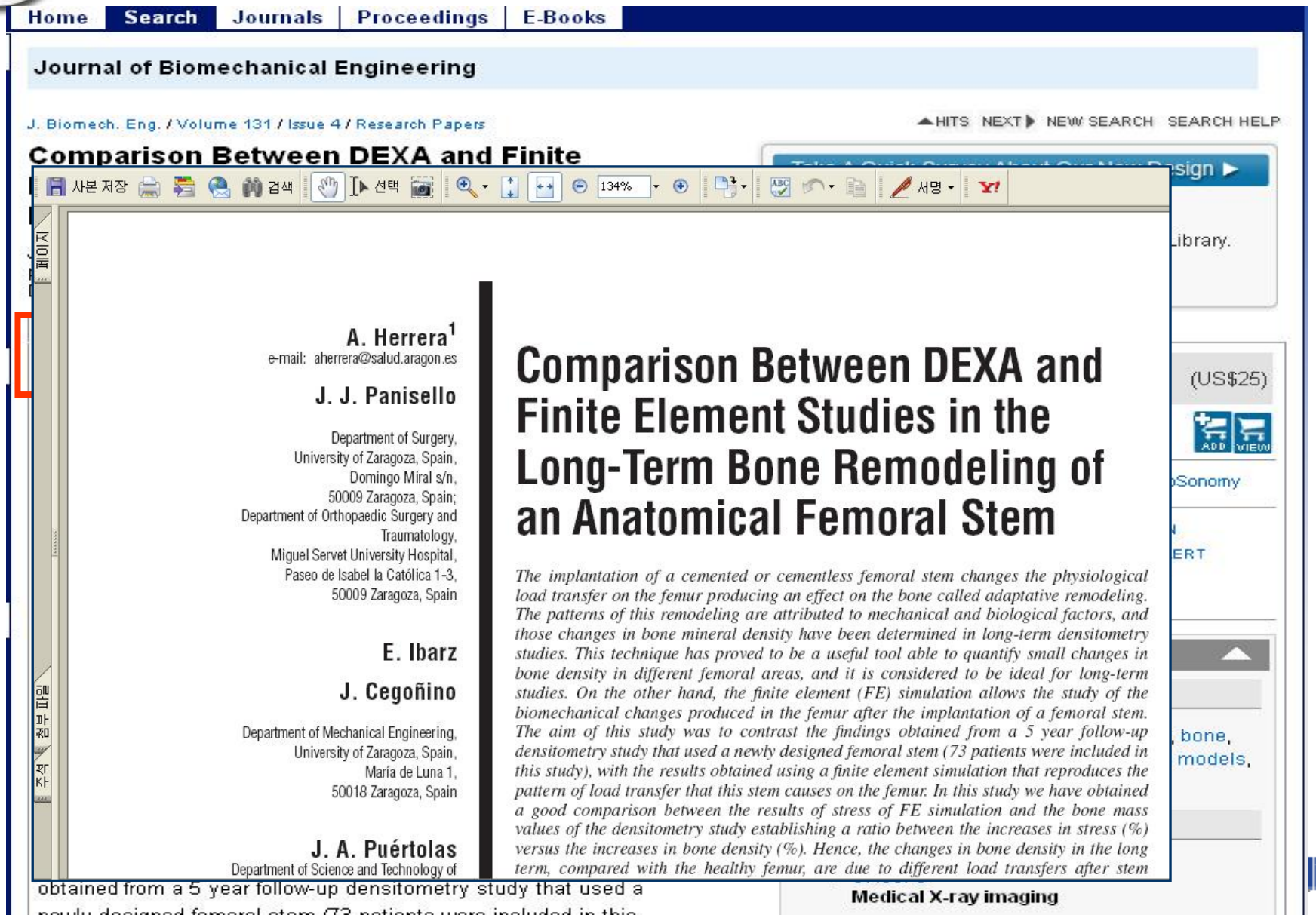
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J. A. Puértolas
Department of Science and Technology of
Comparison Between DEXA and Finite Element Studies in the Long-Term Bone Remodeling of an Anatomical Femoral Stem
The implantation of a cemented or cementless femoral stem changes the physiological load transfer on the femur producing an effect on the bone called adaptative remodeling. The patterns of this remodeling are attributed to mechanical and biological factors, and those changes in bone mineral density have been determined in long-term densitometry studies. This technique has proved to be a useful tool able to quantify small changes in bone density in different femoral areas, and it is considered to be ideal for long-term studies. On the other hand, the finite element (FE) simulation allows the study of the biomechanical changes produced in the femur after the implantation of a femoral stem. The aim of this study was to contrast the findings obtained from a 5 year follow-up densitometry study that used a newly designed femoral stem (73 patients were included in this study), with the results obtained using a finite element simulation that reproduces the pattern of load transfer that this stem causes on the femur. In this study we have obtained a good comparison between the results of stress of FE simulation and the bone mass values of the densitometry study establishing a ratio between the increases in stress (%) versus the increases in bone density (%). Hence, the changes in bone density in the long term, compared with the healthy femur, are due to different load transfers after stem
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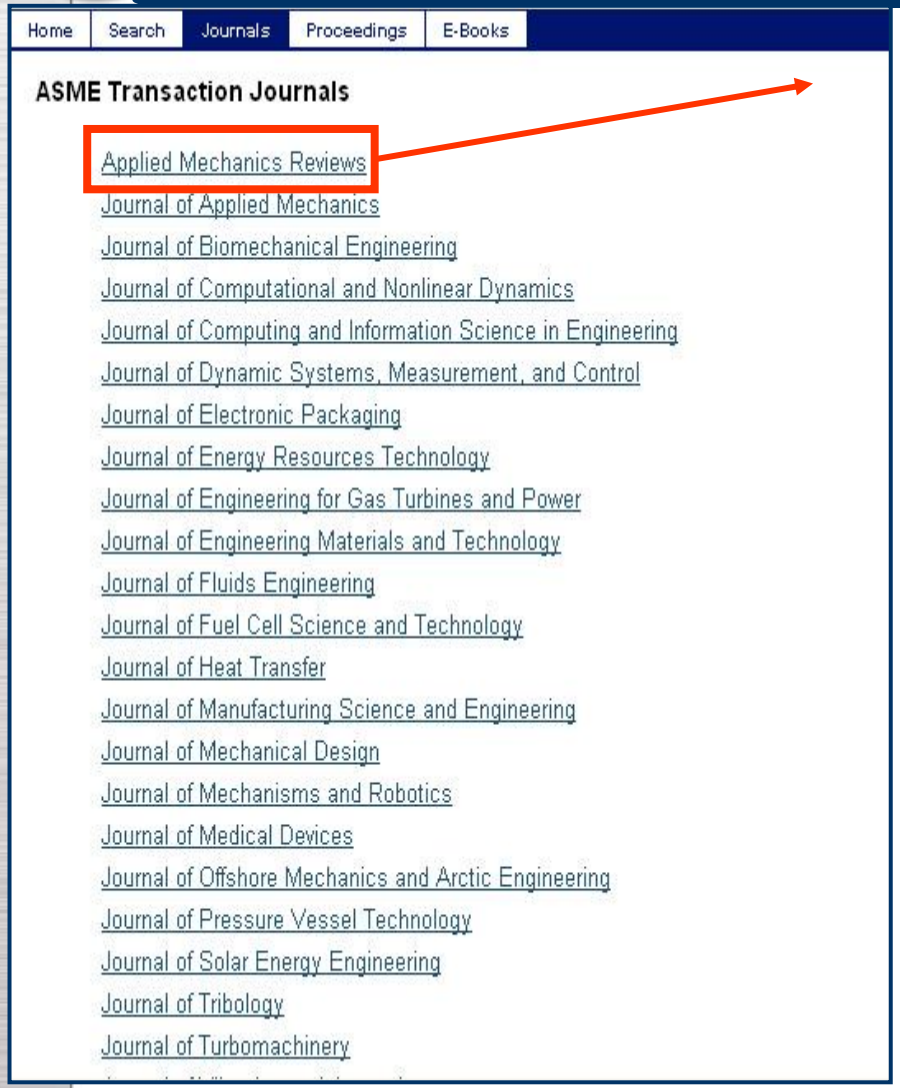

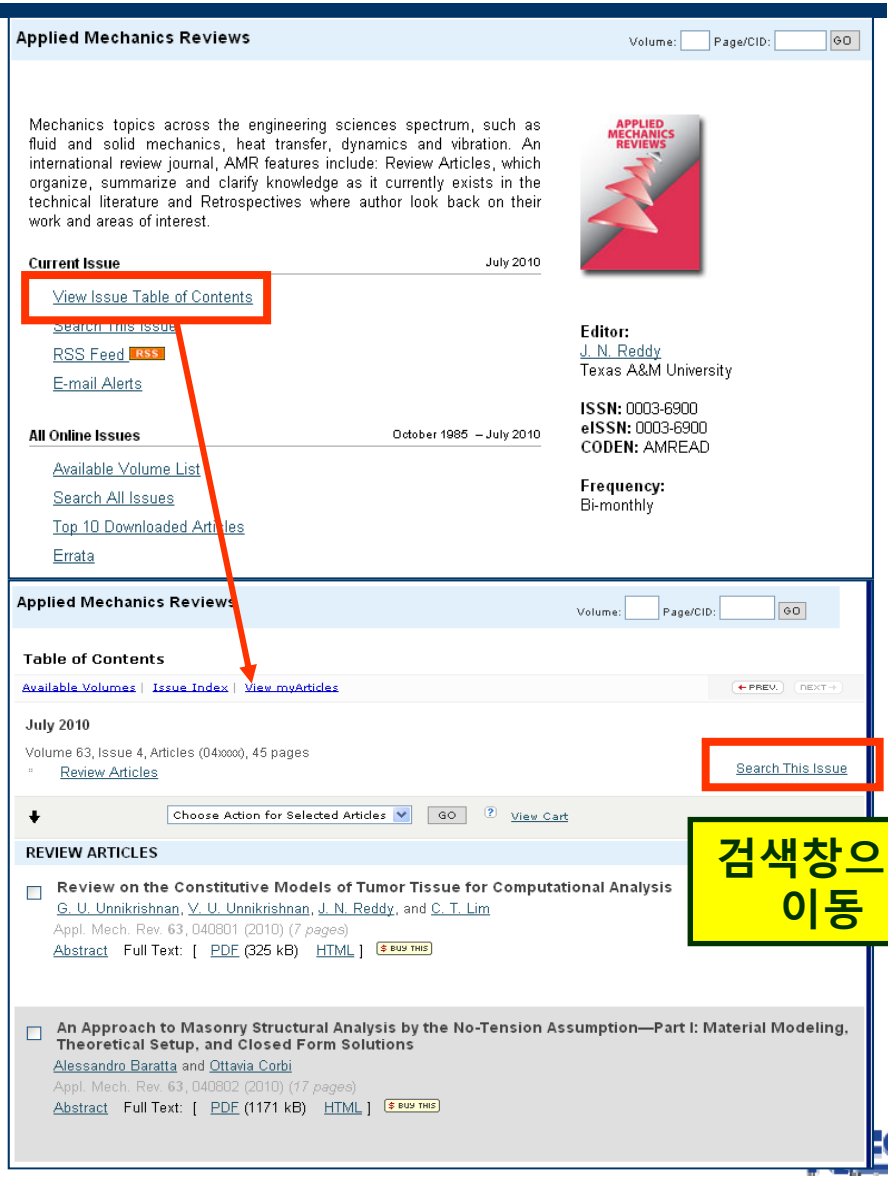

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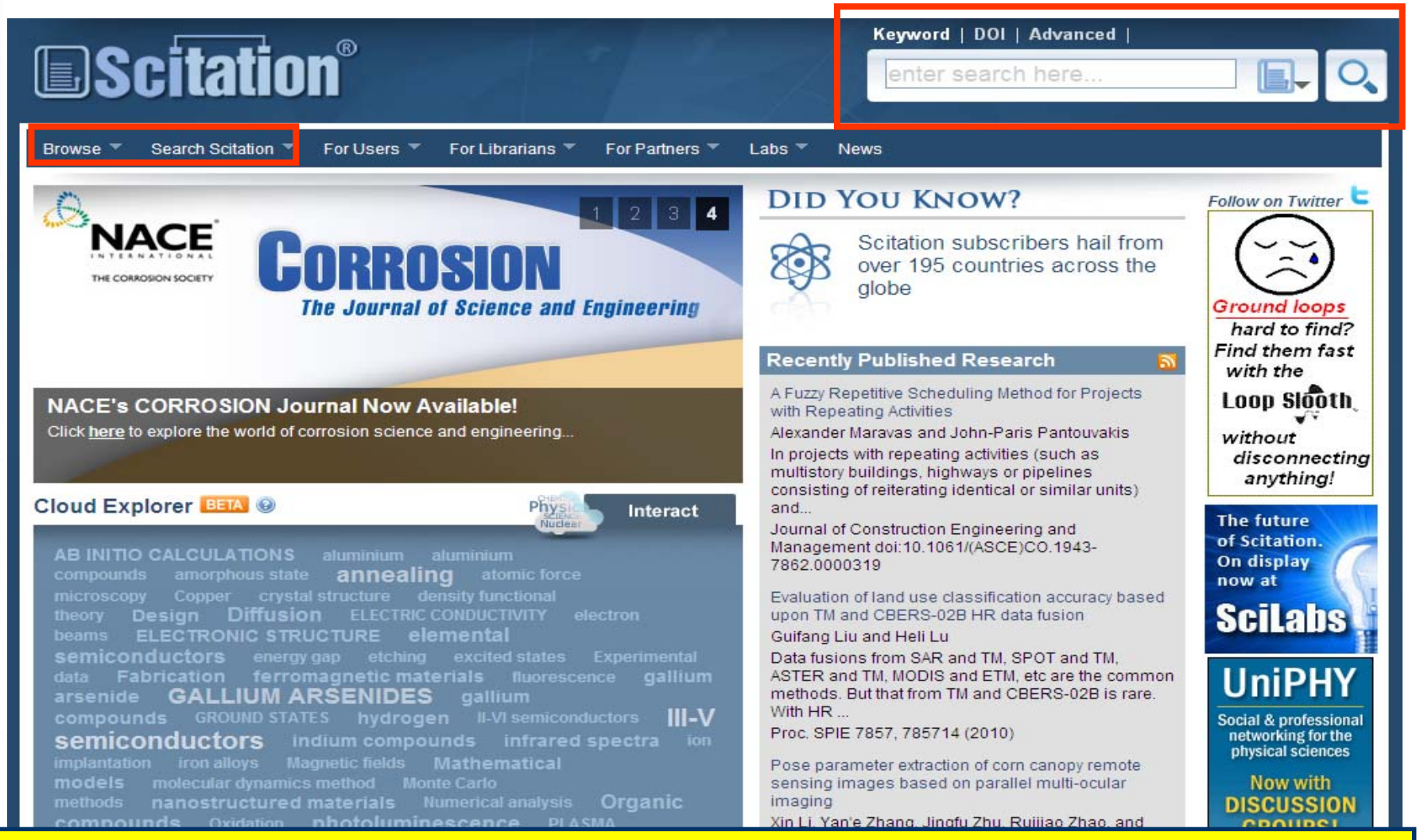

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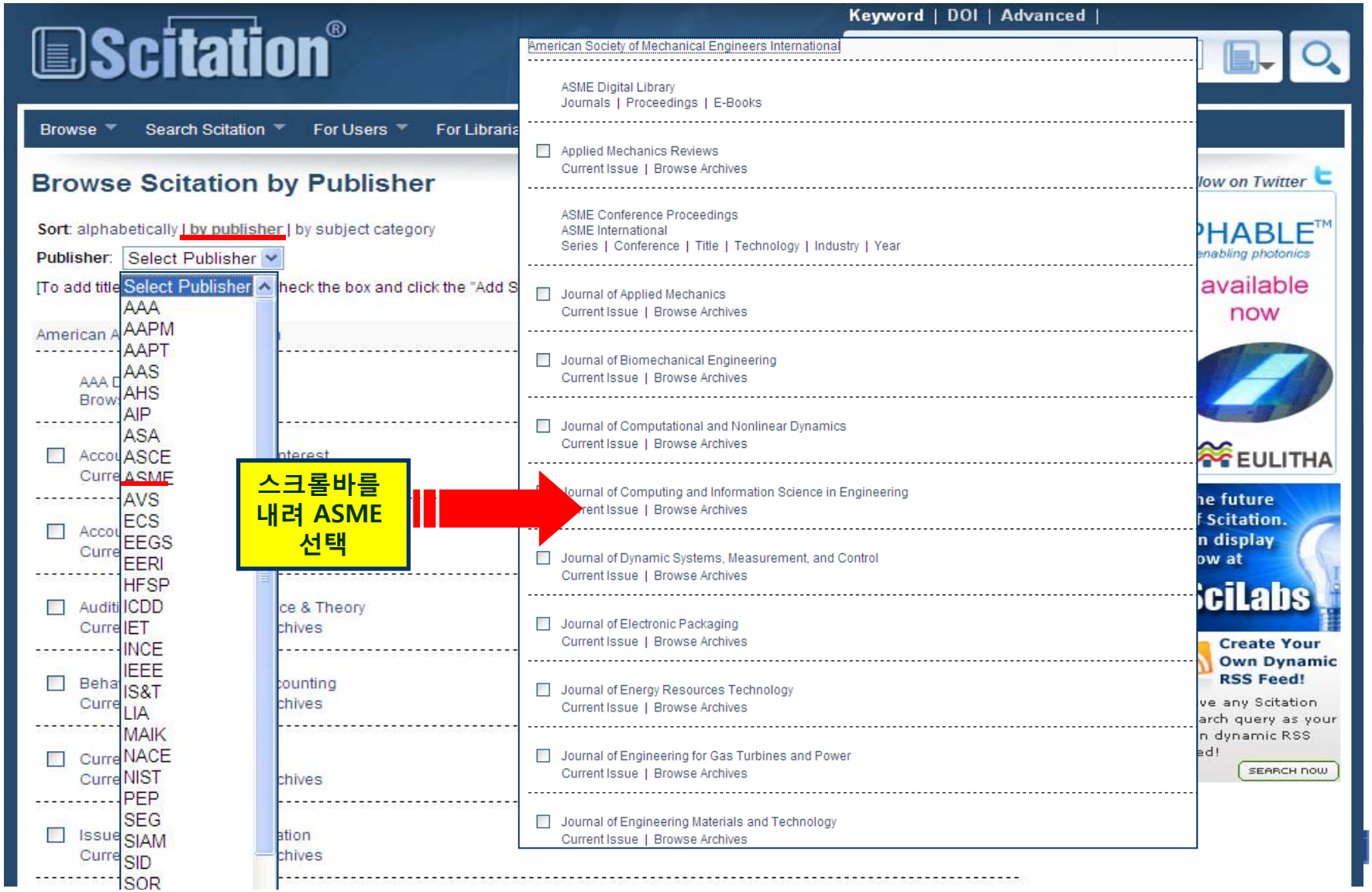

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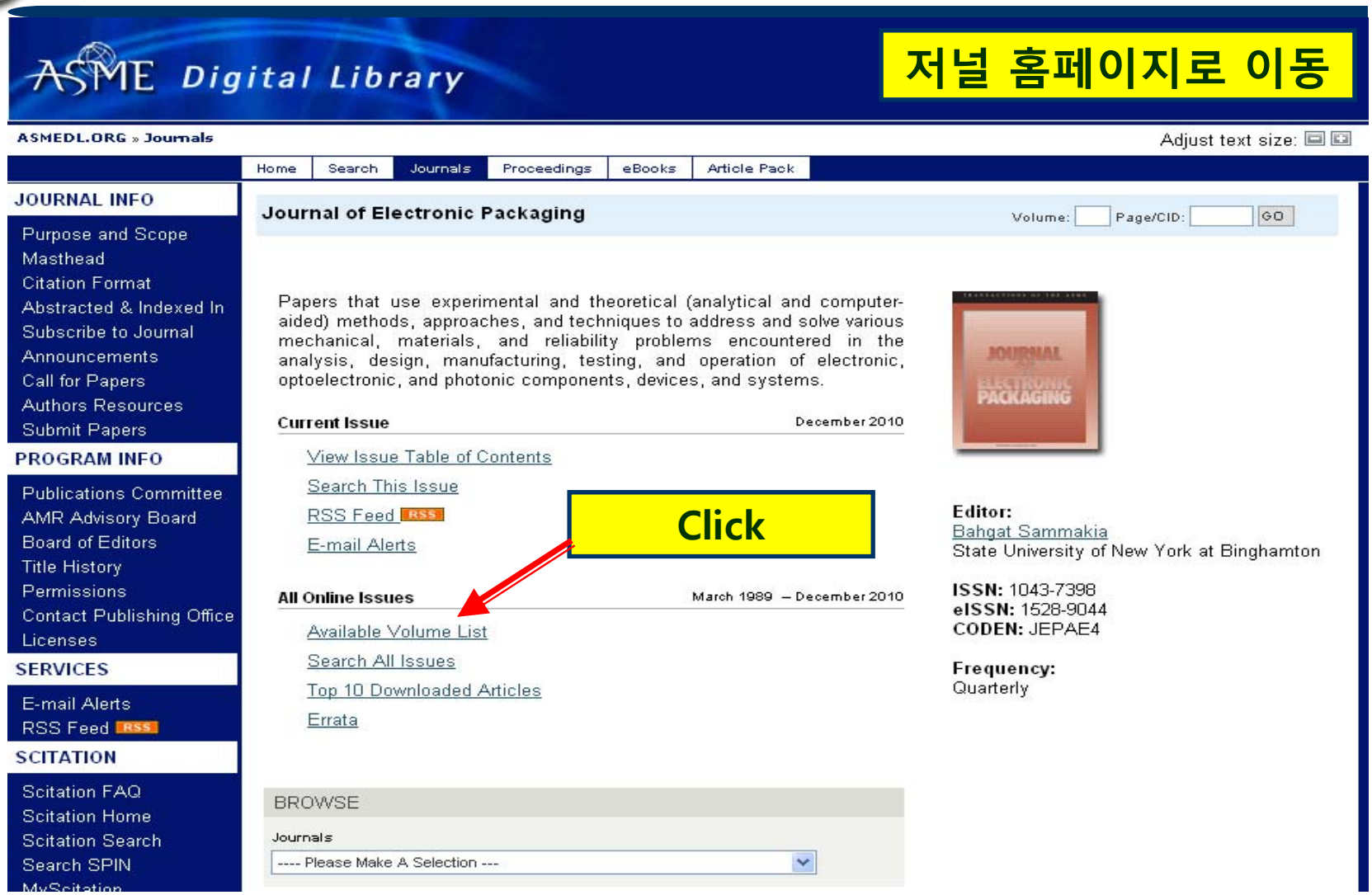

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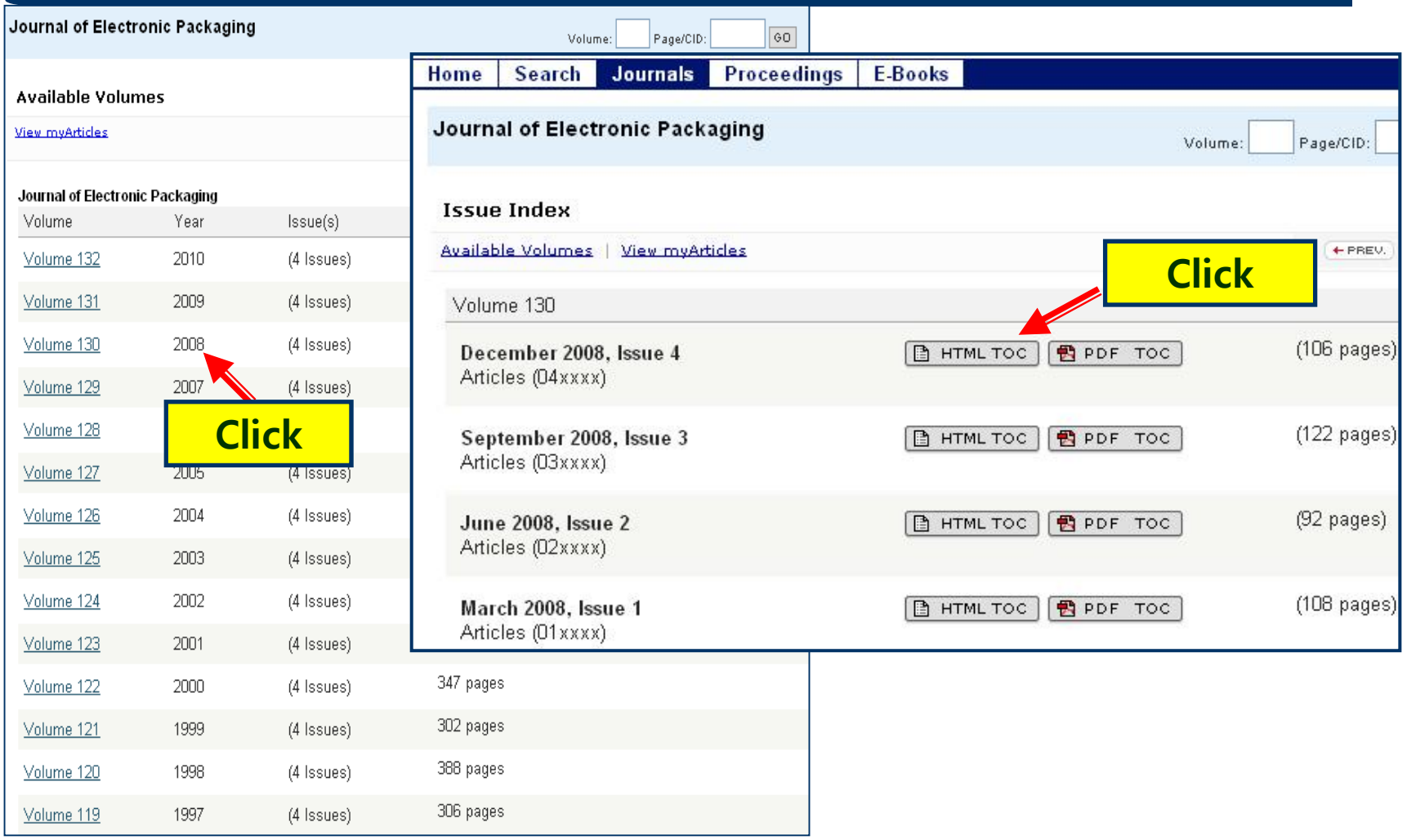

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Electromigration Reliability With Respect to Cu Weight Contents of Sn–Ag–Cu Flip-Chip Solder Joints Under Comparatively Low Current Stressing

This work presents electromigration reliability and patterns of Sn–3Ag–0.5Cu and Sn–3Ag–1.5Cu/Sn–3Ag–0.5Cu composite flip-chip solder joints with Ti/Ni(V)/Cu under bump metallurgy (UBM), bonded on Au/Ni/Cu substrate pads. The solder joints were subjected to an average current density of 5 kA/cm^2 under an ambient temperature of 150°C. Under the situation when electron charges flow from the UBM toward the substrate, Sn diffuses from the Cu–Ni–Sn intermetallic compound developed around the UBM toward the UBM and eventually causes the Ni(V) layer to deform. Electromigration reliability of Sn–3Ag–1.5Cu/Sn–3Ag–0.5Cu composite flip-chip solder joints was found to be better than that of Sn–3Ag–0.5Cu solder joints. According to the morphological observations on cross-sectioned solder joints, a failure mechanism is proposed as follows. Since the deformation of the Ni(V) layer as a result of Sn diffusion toward the UBM is considered as the dominant failure, a greater Cu weight content in the solder joints would trap more Sn in the Sn–Cu interfacial reaction and would therefore retard the diffusion of Sn toward the UBM and hence enhance the electromigration reliability.
[DOI: 10.1115/1.2957325]

Keywords: electromigration, flip-chip, solder joint, reliability, Sn–Ag–Cu, Cu weight

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